

Features

- 802.11a & b/g, UNII, and Hiperlan Applications
- Optimized for 2.4 - 5.8 GHz WLAN
- Low Insertion Loss:
 - 0.7 dB @ 2.4 GHz
 - 0.9 dB @ 5.0 GHz
- High Isolation: 28 dB Typical
- Low Harmonics: <-63 dBc @ 20 dBm
- RoHS* Compliant

Description

M/A-COM's MASW-008206-000DIE is a WLAN / WiMax GaAs PHEMT MMIC Dual SPDT switch. One SPDT (RF2) is optimized for 2.4 GHz WLAN / WiMax. The other (RF5) is optimized for 5.8 GHz WLAN and WiMax applications. Typical applications are for 802.11a and 802.11b/g PC card and access point applications.

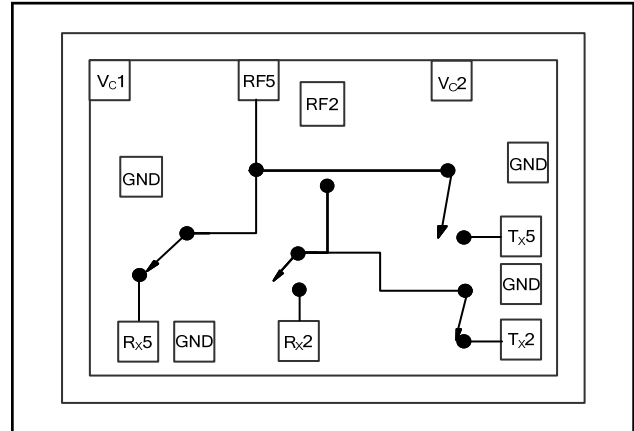
The MASW-008206-000DIE delivers high isolation, low insertion loss and high linearity up to 5.8 GHz. The MASW-008206-000DIE is fabricated using a 0.5 micron gate length GaAs pHEMT process. The process features full passivation for performance and reliability.

Ordering Information ¹

Part Number	Package
MASW-008206-000DIE	Separated Die on Grip Ring

1. Die quantity varies.

Die Bond Pad Layout



Die Bond Pad Configuration

Pad No.	Name	Description
1	V _{c1}	Voltage Control 1
2	GND	Ground
3	R _{x5}	5 GHz R _x Port
4	GND	Ground
5	R _{x2}	2.4 GHz R _x Port
6	T _{x2}	2.4 GHz T _x Port
7	GND	Ground
8	T _{x5}	5 GHz T _x Port
9	GND	Ground
10	V _{c2}	Voltage Control 2
11	RF2	2.4 GHz Antenna Port
12	RF5	5 GHz Antenna Port

Absolute Maximum Ratings ^{2,3}

Parameter	Absolute Maximum
Input Power @ 3 V Control	+32 dBm
Input Power @ 5 V Control	+35 dBm
Operating Voltage	+8 volts
Operating Temperature	-40°C to +85°C
Storage Temperature	-65°C to +150°C

2. Exceeding any one or combination of these limits may cause permanent damage to this device.
3. M/A-COM does not recommend sustained operation near these survivability limits.

* Restrictions on Hazardous Substances, European Union Directive 2002/95/EC.

ADVANCED: Data Sheets contain information regarding a product M/A-COM is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed.

PRELIMINARY: Data Sheets contain information regarding a product M/A-COM has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

- **North America** Tel: 800.366.2266 / Fax: 978.366.2266
 - **Europe** Tel: 44.1908.574.200 / Fax: 44.1908.574.300
 - **Asia/Pacific** Tel: 81.44.844.8296 / Fax: 81.44.844.8298
- Visit www.macom.com for additional data sheets and product information.

M/A-COM Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

GaAs WLAN - WiMax Dual SPDT Switch 2.4 - 5.8 GHz WLAN

M/A-COM Products
Rev. V1

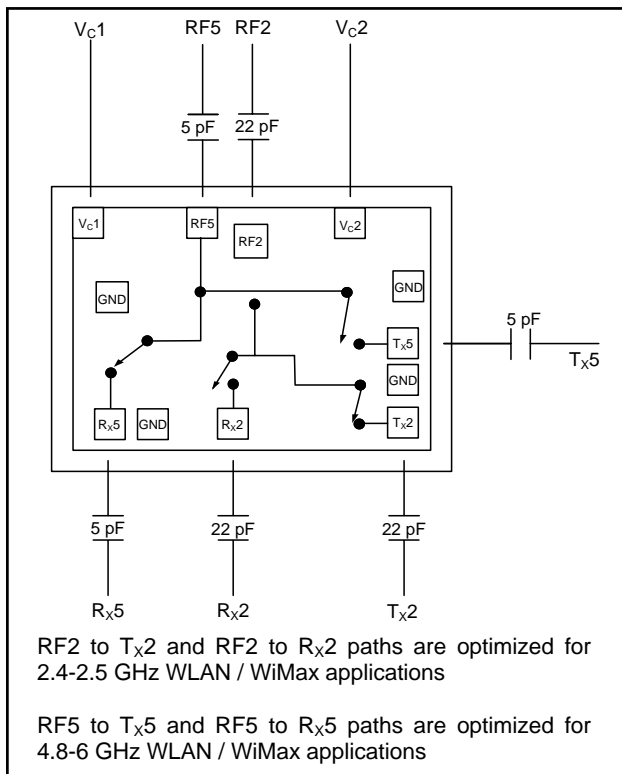
Electrical Specifications^{4,5}: $T_A = 25^\circ\text{C}$, $Z_0 = 50\Omega$, $V_c = 0\text{V} / 3\text{V}$, $\text{Pin} = 0\text{ dBm}$

Parameter	Test Conditions	Units	Min.	Typ.	Max.
Insertion Loss	RF2 to Tx2/Rx2, 2.4 GHz	dB	—	0.7	1.0
	RF5 to Tx5/Rx5, 5.0 GHz	dB	—	0.9	1.2
Isolation	RF2 to Tx2/Rx2, 2.4 GHz	dB	25.5	30.0	—
	RF5 to Tx5/Rx5, 5.0 GHz	dB	21.0	25.0	—
Return Loss	DC - 6 GHz	dB	—	15	—
IP3	RF2 to Tx2/Rx2, 2.4 GHz, 20dBm Total Power, 1MHz Spacing	dBm	—	54	—
	RF5 to Tx5/Rx5, 4.9 GHz, 20dBm Total Power, 1MHz Spacing	dBm	—	55	—
Input P1dB	RF2 to Tx2, 2.4-2.5 GHz	dBm	—	28	—
	RF5 to Tx5, 4.9-5.9 GHz	dBm	—	28	—
Harmonics	RF2 to Tx2, 2.4-2.5 GHz, 20 dBm	dBm	—	-63	—
	RF5 to Tx5, 4.9-5.9 GHz, 20 dBm	dBm	—	-67	—
Control Current	$ V_c = 3\text{V}$	μA	—	<1	10.0
$T_{\text{RISE}} / T_{\text{FALL}}$	10% - 90% RF, 90% - 10% RF	nS	—	22	—
$T_{\text{ON}} / T_{\text{OFF}}$	50% Control - 90% RF, 50% Control - 10% RF	nS	—	30	—

4. External blocking capacitors on all RF ports.

5. Electrical min/max are guaranteed in die form only.

Application Schematic



Truth Table^{6,7,8}

Control V_{c1}	Control V_{c2}	RF2 - Tx2 RF5 - Rx5	RF2 - Rx2 RF5 - Tx5
1	0	On	Off
0	1	Off	On

6. For positive voltage control, external DC blocking capacitors are required on all RF ports.

7. Differential voltage, $V(\text{state } 1) - V(\text{state } 0)$, must be +2.7 V minimum and must not exceed +5 V.

8. 0 = $0 \pm 0.3\text{V}$, 1 = +2.7 V to +5 V.

ADVANCED: Data Sheets contain information regarding a product M/A-COM is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed.

PRELIMINARY: Data Sheets contain information regarding a product M/A-COM has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

• **North America** Tel: 800.366.2266 / Fax: 978.366.2266

• **Europe** Tel: 44.1908.574.200 / Fax: 44.1908.574.300

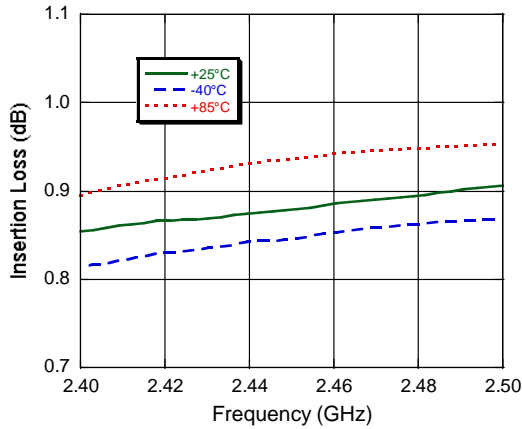
• **Asia/Pacific** Tel: 81.44.844.8296 / Fax: 81.44.844.8298

Visit www.macom.com for additional data sheets and product information.

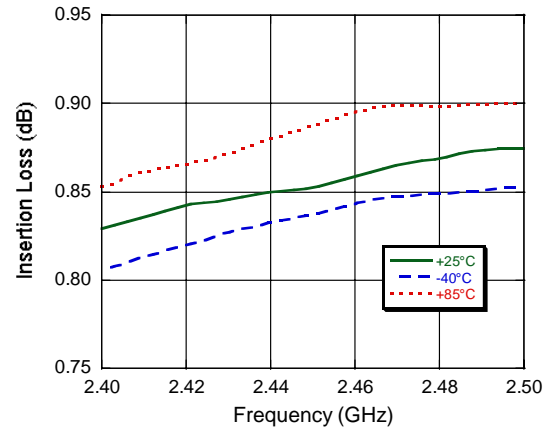
M/A-COM Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

Typical Performance Curves @ 2.4 GHz (plots = chip on board assembly)

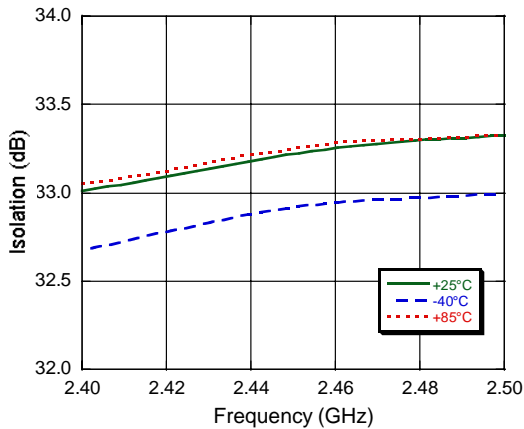
T_x Insertion Loss



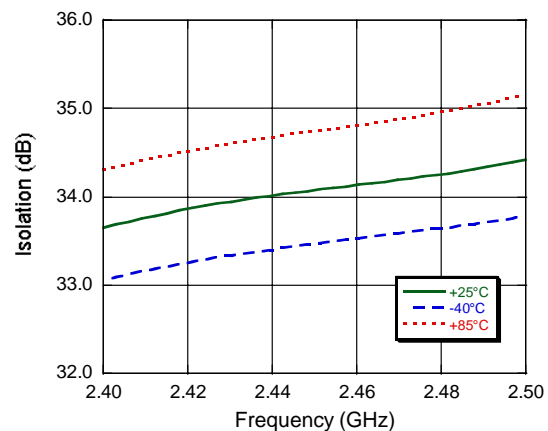
R_x Insertion Loss



T_x Isolation

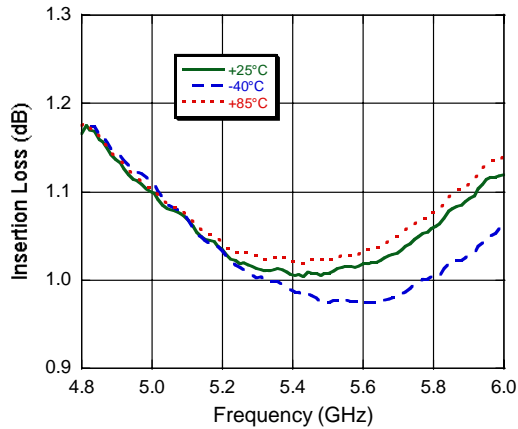


R_x Isolation

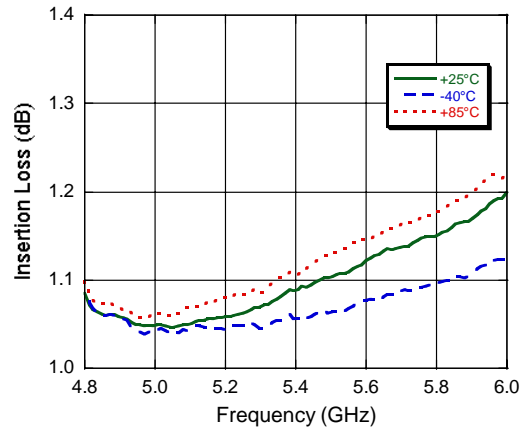


Typical Performance Curves @ 5.0 GHz (plots = chip on board assembly)

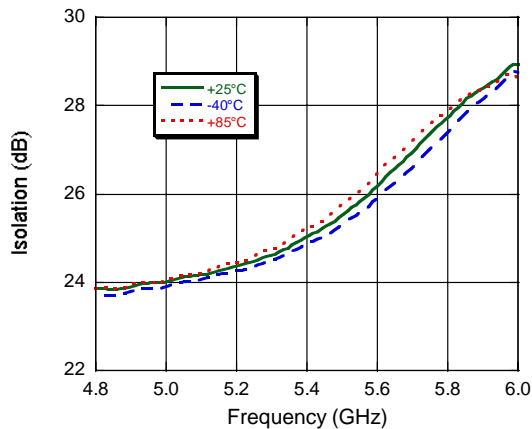
T_x Insertion Loss



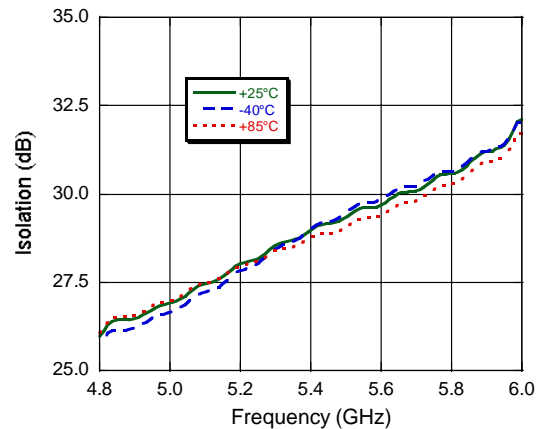
R_x Insertion Loss



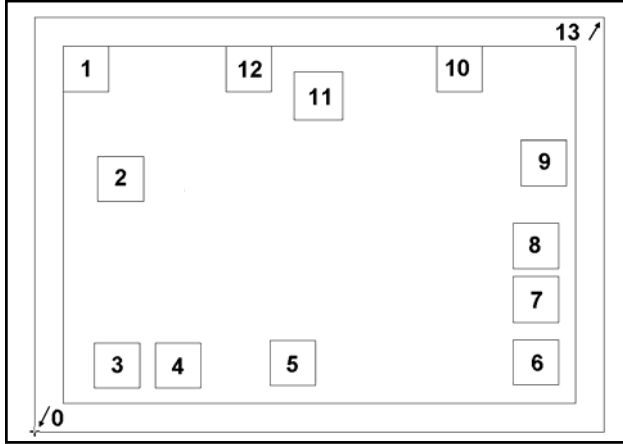
T_x Isolation



R_x Isolation



Outline Drawing



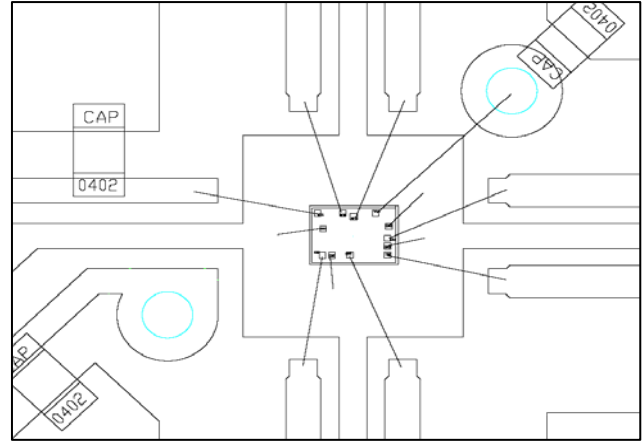
Pad Configuration ⁸

Die Size: 890 x 650 μm (nominal)

Pad No.	X (μm) nominal	Y (μm) nominal	Pad Size (μm)
0	0	0	Lower left edge of die
1	80.5	569.5	71 x 71
2	134.5	397	71 x 71
3	129	104	71 x 71
4	224	104	71 x 71
5	403.75	108	71 x 71
6	783.5	109	71 x 71
7	783.5	208	71 x 71
8	783.5	292	71 x 71
9	795.25	421.75	71 x 71
10	664	569.5	71 x 71
11	443	527	76 x 76
12	334.75	569.5	71 x 71
13	890	650	Upper right edge of die

8. All X,Y dimensions are at bond pad center.

Chip mounted to PWB for testing purposes



Qualification

Qualified to M/A-COM specification REL-201, Process Flow -2.

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

Gallium Arsenide Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling MASW-008206-000DIE, which are Class Zero (100 V) devices.